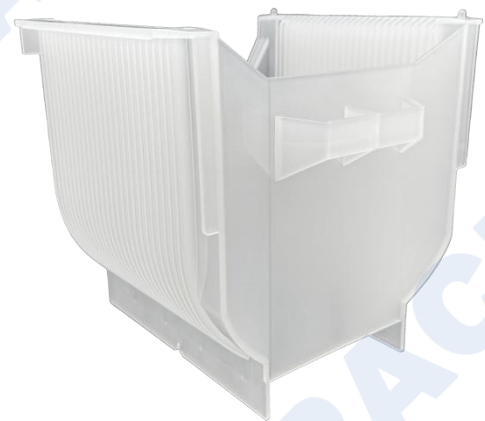
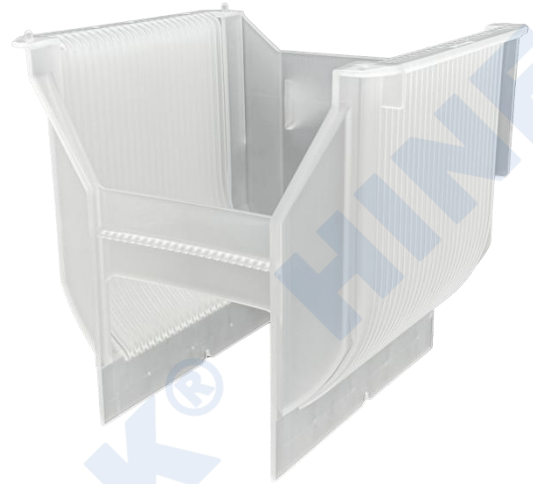


Hiner-pack® MCS-PP Cassette 200 mm

Precision-molded cassette ensuring accurate wafer alignment and maximum cleanliness

Wafer cassettes are used to transport and store wafers during semiconductor manufacturing operations. For the general process, wafer cassette is engineered for in-fab transfer and temporary storage of wafers between process stations. Also referred to as wafer boats, they are designed to house or carry several wafers of the same size and are available in a range of materials to support specific applications, such as thermal processing. This wafer cassette is molded from polypropylene, they tolerate typical fab temperatures and are available in natural or conductive material. These wafer cassettes, designed for advanced wafer transport, provide precise wafer access, reliable equipment operation, and secure wafer protection, address automation, contamination control, and productivity requirements for today's fabs. It can collocation with wafer storage boxes to protect wafers.



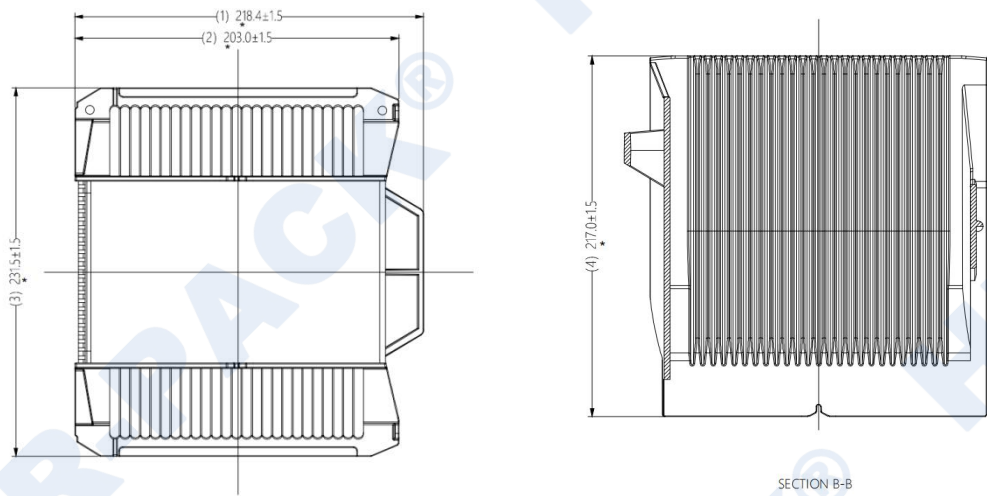
SPECIFICATIONS

- 218.4 mm L × 231.5 mm W × 217 mm H (8.6" × 9.11" × 8.54")
- Maximum load capacity is 25 pieces

FEATURES & BENEFITS

- Lightweight PP construction ideal for in-fab transfer
- Compatible with automation and cassette-standard tools
- Available in multiple colors to facilitate process identification
- Available in multiple materials to cope with different requirements for chemical resistance
- Moderate temperature resistance material

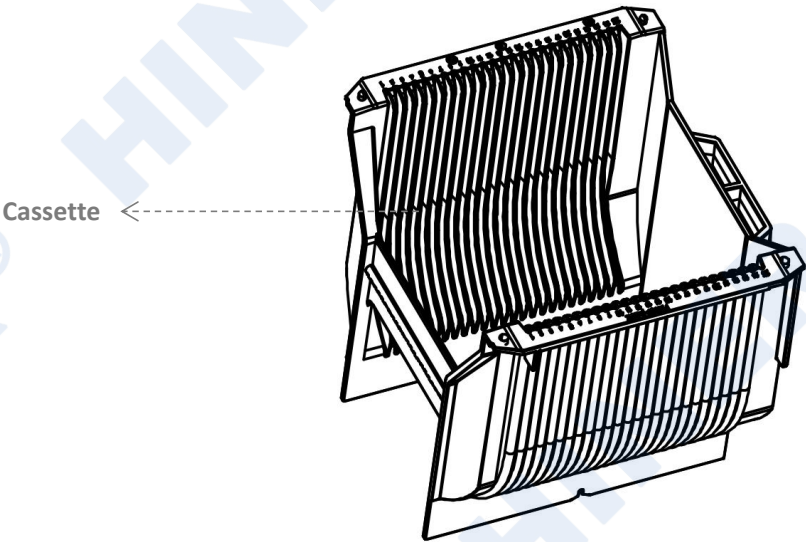
DIMENSION



BASIC INFORMATION

Part Number	Material	Wafer Size
MCS-8/25-NP	PP	200 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm ³
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m ²
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m ²
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	23°C	6 kg.cm/cm
	-20°C	--- notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



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